Press release:
Purchase program Melexis NV shares
Intermediate declaration by the Board of Directors.
Tessenderlo, Belgium – March 7th, 2011 at 18.00 hrs CET

The board of directors of Melexis Tessenderlo NV has decided on August 20, 2010 to start with the purchase of shares Melexis NV on Euronext Brussels (press release August 24, 2010).

Melexis Tessenderlo NV announces today that it acquired 40.350 shares during the period February 28, 2011 till March 4, 2011.

For further information, please go to http://www.melexis.com/investor_info_tshares.aspx or contact:
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About Melexis
Melexis Microelectronic Integrated Systems N.V. (Euronext Brussels:MELE) imagines, creates and delivers innovative mixed signal integrated circuits. Melexis ICs are driving green solutions that enable our customers to bring more energy efficient automotive systems to market. Melexis product portfolio addresses 4 classes of ICs; Sensor, Optoelectronic, Wireless and Actuators. Sensors include magnetic, MEMs, and sensor interface ICs. Optoelectronic products encompass linear arrays, single point sensors, infrared thermometers and CMOS wide dynamic range and night vision cameras. Wireless ICs focus on RKE, TPMS, ISM band applications, NFC, RFID reader and smart tag solutions. Actuator ICs cover LIN and CAN bus networking ICs and advanced BLDC motor driver technology. Melexis is proud of its participation toward reducing the human race’s global environmental footprint. For more information, visit http://www.melexis.com.

Disclaimer
Except for those statements that report the Company’s historical results, the statements being made are forward looking statements. Actual results could differ materially from those projected in the forward-looking statements. Factors which could cause actual results to differ from expectations include the following: volatility in supply and demand affecting revenues and market prices, price and availability of silicon foundry, assembly and test prices, assembly and test subcontract capacity required to meet financial targets and/or meet backlog requirements, risks and delays associated with bringing up new production capabilities or with deliveries from subcontractors, timing and market acceptance of new products, increased expenses associated with new product acceptance of new products, increased expenses associated with new product introductions of process changes, delays in developing or achieving volume production of new products, which can result in delays or failure to contribute to revenues and profits, ability of the Company to maintain its customer and vendor base and delays in and/or inability in raising additional capital.